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FOR IMMEDIATE RELEASE

**VIKING INTERWORKS SHIPS COST-EFFECTIVE, HIGH-PERFORMANCE
DRAM MODULES USING NEW STACKING TECHNOLOGY***DDR1 Modules Available Now With DDR2 – Available Mid 2005*

RANCHO SANTA MARGARITA, Calif. – March 8, 2005 – Viking InterWorks, a Sanmina-SCI Company (Nasdaq NM: SANM), today announced a new cost-effective DRAM stacking solution based on its proprietary version of chip-scale packaging (CSP) technology. This innovative patent-pending packaging technique enables the design and manufacture of cost-effective, high-density DRAM modules for large servers, telecom switches and storage applications. A complete offering of SoDIMM modules designed for space-constrained embedded applications is also planned for late next year.

The standard height (1.2 inch) 184 pin RDIMM (Registered DIMM) portion of the product line consists of DDR modules in densities of 1GByte (1 rank), 2GByte (2 rank) and 4GByte (4 rank) with speed grades of PC2100, PC2700 and PC3200 across all densities. These modules are manufactured using 512Mb DRAM components.

“This CSP technology enables stacking of very small DRAM components two high or four high in a cost-effective and reliable manner,” said Mark Ellsberry, Vice President of Marketing for Viking InterWorks. “As a result, this technology has led to a very low profile (VLP) registered DIMM with a standard height of 0.72 inches, yet still achieves densities of 1GByte (1 rank), 2GByte (2 rank) and 4GByte (4 rank) targeted for mainstream server applications. All other dimensions for this module are the same as a standard RDIMM, and the modules come in speed grades of PC2100, PC2700 and PC3200.”

The proprietary CSP technology incorporated in these high-density modules is capable of vastly improving electrical and thermal performance as compared to the mainstream standard DRAM package (TSOP). The simple flip-chip construction has reduced stray impedances, creating greater operating margins for the modules electrical timing parameters, resulting in simple-system designs and higher-production yields.

“The thermal performance of the CSP is comparable to FBGA and significantly better than today’s current DRAM package. The DRAM industry is moving to the improved FBGA package which has presented significant problems for stacking components to achieve the high-density modules required for today’s high-performance blade servers and storage devices,” added Ellsberry. “This proprietary CSP approach to building memory components uses a novel technique of mounting chips on an interposer with carefully controlled thermal coefficient of expansion, resulting in cost-effective and reliable stacking of two and four high-chip stacks.”

These new lead-free packages provide excellent thermal characteristics compared to other technologies and increased reliability due to the matched thermal characteristics of the silicon and the substrate. The CSP technology combines superior electrical performance with the ability to stack packages and is currently available through Viking InterWorks. Future Viking InterWorks’ plans include the introduction of DDR2 DRAM technology to both RDIMM and VLP RDIMM modules by mid 2005. DDR2 versions of SoDIMM modules will be available by the end of 2005. These modules will be available in PC2-3200, PC2-4200 and PC2-5300 speed grades. For more information, visit www.vikinginterworks.com.

Part numbers for a selection of these DIMMS are listed below:

VR4VR567224ECK – VLP 2GB 2Rankx4 PC2700
VR4VR567224ECP – VLP 2GB 2Rankx4 PC3200
VR4VR127224EPK – VLP 4GB 4Rankx4 PC2700
VR4VR127224EPP – VLP 4GB 4Rankx4 PC3200
VR4CR127224ECK – Standard 4GB 4Rankx4 PC2700
VR4CR127224ECP – Standard 4GB 4Rankx4 PC3200

About Sanmina-SCI

Sanmina-SCI Corporation is a leading electronics contract manufacturer serving the fastest-growing segments of the global electronics manufacturing services (EMS) market. Recognized as a technology leader, Sanmina-SCI provides end-to-end manufacturing solutions, delivering unsurpassed quality and support to OEMs primarily in the communications, defense and aerospace, industrial and medical instrumentation, computer technology, and multimedia sectors. Sanmina-SCI has facilities strategically located in key regions throughout the world. More information regarding the Company is available at www.sanmina-sci.com.

Sanmina-SCI Safe Harbor Statement

The foregoing, including the discussion regarding the company's future prospects, contains certain forward-looking statements that involve risks and uncertainties, including uncertainties associated with economic conditions in the electronics industry, particularly in the principal industry sectors served by the company, changes in customer requirements and in the volume of sales to principal customers, the ability of Sanmina-SCI to effectively assimilate acquired businesses and achieve the anticipated benefits of its acquisitions, and competition and technological change. The company's actual results of operations may differ significantly from those contemplated by such forward-looking statements as a result of these and other factors, including factors set forth in the company's fiscal year 2003 Annual Report on Form 10-K filed on December 9, 2003 and 10-Q filed on August 9, 2004, with the Securities Exchange Commission.

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